



SOT457-1

TSOP6, plastic thin small outline package; 6 leads; 0.95 mm pitch; 2.9 mm x 1.5 mm x 1 mm body

9 June 2020

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	TSOP6
Package style descriptive code	TSOP (thin small outline package)
Package body material type	P (plastic)
JEITA package outline code	SC-74
Mounting method type	S (surface mount)
Issue date	16-03-2006
Manufacturer package code	SOT457-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.7	2.9	3.1	mm
package width	1.3	1.5	1.7	mm
seated height	0.9	1	1.1	mm
nominal pitch	-	0.95	-	mm
actual quantity of termination	-	6	-	



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2 Package outline

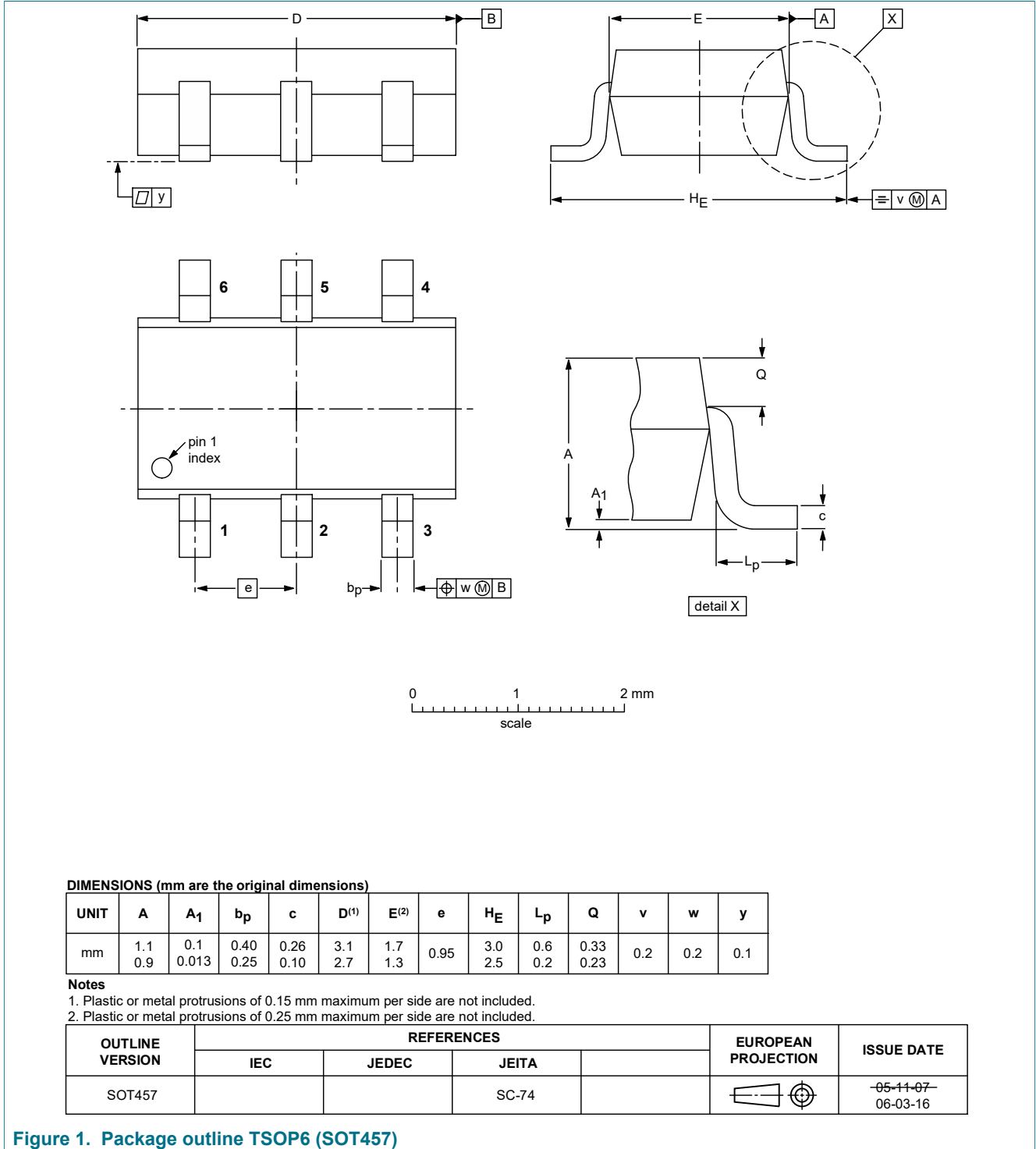
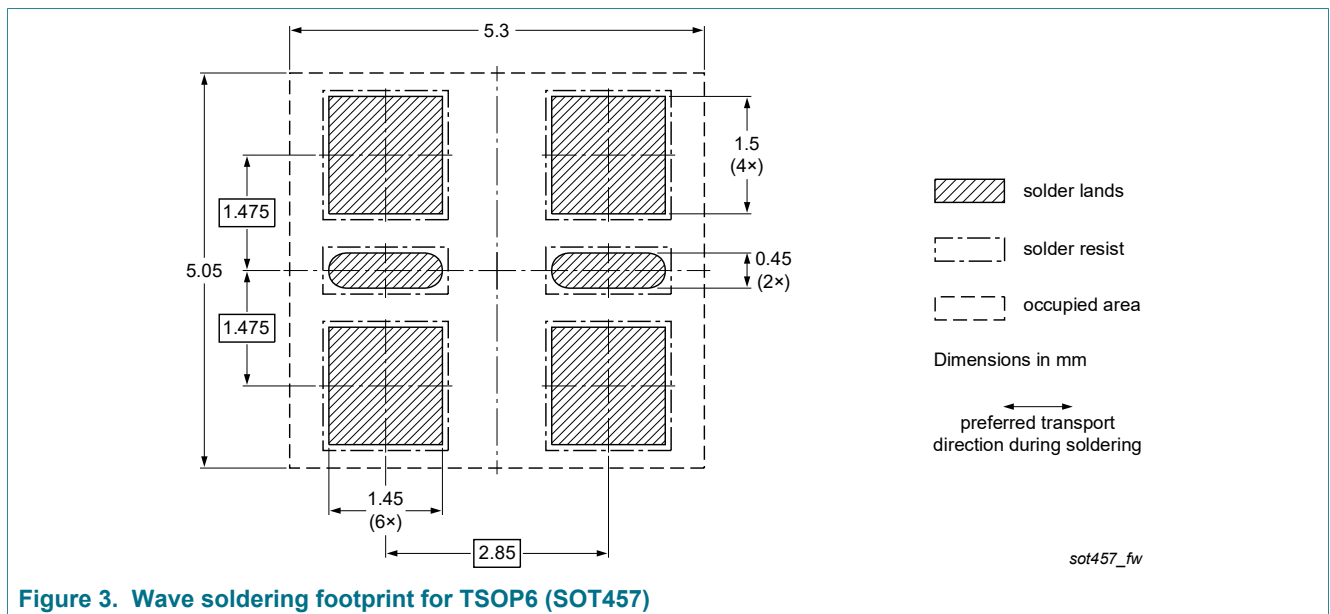
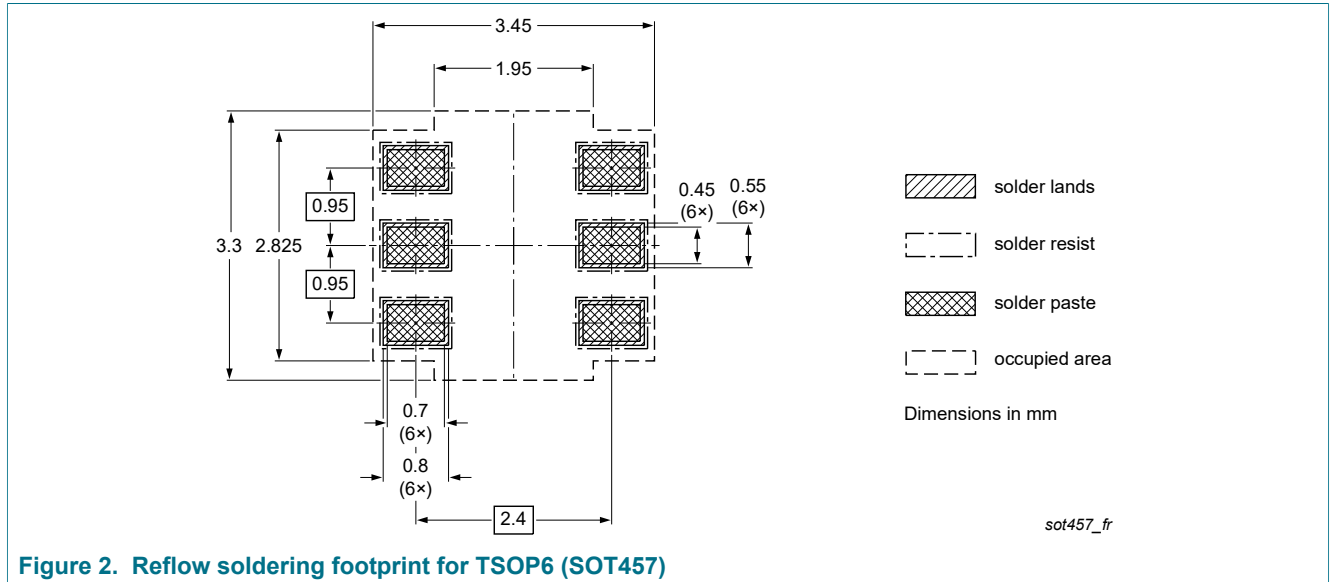


Figure 1. Package outline TSOP6 (SOT457)

3 Soldering



4 Legal information

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